

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-8 (Canceled)

Claim 9 (New): A method of controlling semiconductor manufacturing equipment, comprising:

sampling a plurality of sample data of at least one parameter which represents a manufacturing condition, under a normal operating state of the semiconductor manufacturing equipment;

generating a Mahalanobis space based on the plurality of sample data;

calculating a Mahalanobis distance based on the Mahalanobis space and a group of operating data of the at least one parameter measured during an operating state of the semiconductor manufacturing equipment; and

stopping operation of the semiconductor manufacturing equipment when the Mahalanobis distance exceeds a threshold value.

Claim 10 (New): A semiconductor device produced in accordance with the method of claim 9.

Claim 11 (New): The method of controlling semiconductor manufacturing equipment of claim 9, wherein the at least one parameter is plasma emission intensity.

Claim 12 (New): The method of controlling semiconductor manufacturing equipment of claim 9, further comprising generating an alarm when the Mahalanobis distance exceeds the threshold value.

Claim 13 (New): A method of controlling semiconductor manufacturing equipment, comprising:

- sampling a plurality of sample data of at least one parameter which represents a manufacturing condition, under a normal operating state of the semiconductor manufacturing equipment;

- standardizing the plurality of sample data using a standardizing calculator, to provide a plurality of standardized sample values;

- measuring a group of operating data of the at least one parameter during an operating state of the semiconductor manufacturing equipment;

- standardizing the group of operating data using the standardizing calculator, to provide a group of standardized operating values;

- calculating a similarity value using a value calculator, based on the standardized sample values and the standardized operating values; and

- stopping operation of the semiconductor manufacturing equipment when the similarity value exceeds a threshold value.

Claim 14 (New): A semiconductor device produced in accordance with the method of claim 13.

Claim 15 (New): The method of controlling semiconductor manufacturing equipment of claim 13, further comprising:

obtaining a set of matrix elements using a matrix calculator, based on the standardized sample values,

said calculating uses the set of matrix elements and the standardized operating values to calculate the similarity value.

Claim 16 (New): The method of controlling semiconductor manufacturing equipment of claim 13, wherein the semiconductor manufacturing equipment is a plasma etching system,

the at least one parameter represents an intensity of a desired wavelength of plasma emission for forming etched holes on a semiconductor substrate used for forming a semiconductor wafer.

Claim 17 (New): The method of controlling semiconductor manufacturing equipment of claim 13, wherein the standardizing calculator uses an equation

$$Y_{n,m} = (Y'_{n,m} - Ave_n)/\sigma_n,$$

wherein $Y'_{n,m}$ is a sample data at an appointed time X_n in m time sampling, Ave_n is an average of a group of sample data measured at time X_n , σ_n is a standard deviation of data at time X_n , and $Y_{n,m}$ is a standardized sample value at X_n ,

whereby n is an integer from 1 to n and m is an integer from 1 to m .

Claim 18 (New): The method of controlling semiconductor manufacturing equipment of claim 17, wherein the matrix calculator uses an equation

$$r_{ij} = r_{ji} = \frac{1}{m} \sum_{p=1}^m Y_{ip} Y_{jp} ,$$

wherein r_{ij} and r_{ji} are matrix elements and i and j are integers from 1 to n .

Claim 19 (New): The method of controlling semiconductor manufacturing equipment of claim 18, wherein the value calculator uses an equation

$$D^2 = \frac{1}{n} \sum_{i=1}^n \sum_{j=1}^n a_{ij} Y_i Y_j ,$$

wherein D is the similarity value and a_{ij} are matrix elements of an inverse matrix of the set of matrix elements obtained by the matrix calculator during said obtaining.

Claim 20 (New): The method of controlling semiconductor manufacturing equipment of claim 19, wherein the threshold value is within a range of 2 to 4.

Claim 21 (New): The method of controlling semiconductor manufacturing equipment of claim 13, wherein the at least one parameter is plasma emission intensity.

Claim 22 (New): The method of controlling semiconductor manufacturing equipment of claim 13, further comprising generating an alarm when the similarity value exceeds the threshold value.